



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSS670S2L H6327	Issued	02. June 2021
MA#	MA001623878		
Package	PG-SOT23-3-5	Weight*	9.36 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		403	
	noble metal	gold	7440-57-5	0.015	0.16		1564	
	inorganic material	silicon	7440-21-3	0.223	2.39	2.59	23863	25830
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	non noble metal	copper	7440-50-8	3.000	32.07	32.21	320657	322009
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	768	768
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6050	
	plastics	epoxy resin	-	1.217	13.01		130076	
	inorganic material	silicondioxide	60676-86-0	4.387	46.87	60.48	468879	605005
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	15992	15992
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30396	30396
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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